

1SS119

Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0564-0300

(Previous: ADE-208-180B)

Rev.3.00 Mar 23, 2005

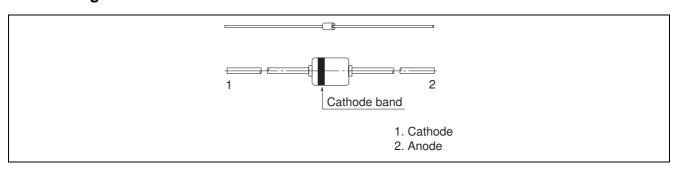
Features

- Low capacitance. (C = 3.0 pF max)
- Short reverse recovery time. $(t_{rr} = 3.5 \text{ ns max})$
- Small glass package (MHD) enables easy mounting and high reliability.

Ordering Information

Type No.	Cathode band	Package Name	Package Code (Previous Code)
1SS119	Light Blue	MHD	GRZZ0002ZC-A
			(MHD)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Peak reverse voltage	V _{RM}	35	V
Reverse voltage	V _R	30	V
Average rectified current	I ₀	150	mA
Peak forward current	I _{FM}	450	mA
Non-Repetitive peak forward surge current	I _{FSM} *	1	Α
Power dissipation	Pd	250	mW
Junction temperature	Tj	175	°C
Storage temperature	Tstg	−65 to +175	°C

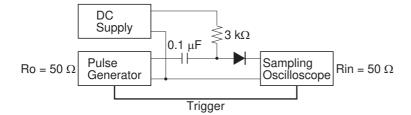
Note: Within 1s forward surge current.

Electrical Characteristics

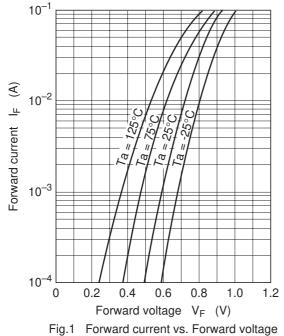
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	0.8	V	I _F = 10 mA
Reverse current	I _R	_	_	0.1	μΑ	V _R = 30 V
Capacitance	С	_	_	3.0	pF	V _R = 1 V, f = 1 MHz
Reverse recovery time	t _{rr} *	_	_	3.5	ns	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 50 \Omega$

Note: Reverse recovery time test circuit



Main Characteristic



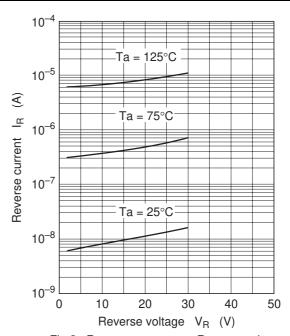
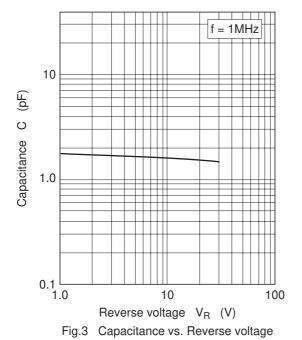
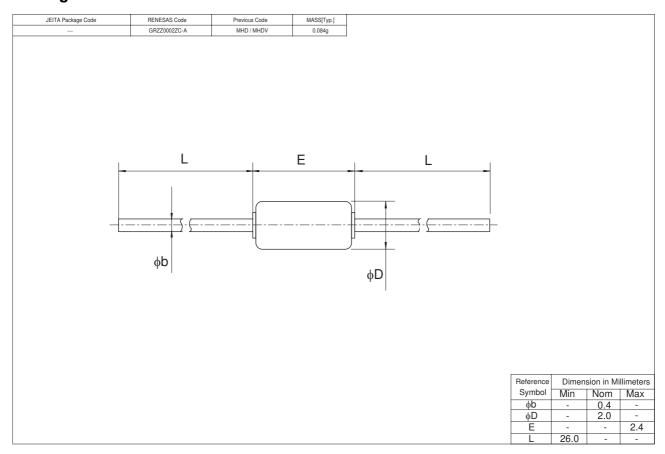


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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